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# Evaluation of a Hybrid Multi-Level Flying-Capacitor Bridge-Leg Topology for Beyond 99% Power Conversion Efficiency



Jon Azurza et al.

Swiss Federal Institute of Technology (ETH) Zurich Power Electronic Systems Laboratory www.pes.ee.ethz.ch

Feb. 20<sup>th</sup>, 2019



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# Evaluation of a Hybrid Multi-Level Flying-Capacitor Bridge-Leg Topology for Beyond 99% Power Conversion Efficiency



J. Azurza, M. Guacci, D. Neumayr, J. W. Kolar

Swiss Federal Institute of Technology (ETH) Zurich Power Electronic Systems Laboratory www.pes.ee.ethz.ch In collaboration with:



Feb. 20<sup>th</sup>, 2019

Acknowledgements: K. L. Pally



#### ► Towards Ultra-High Efficiency





# Agenda





# Pushing the Barriers: Existing Solutions



#### Ultra-High Efficiency

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• Ultra-High Power Density



# ► Ultra-High Efficiency (1)

Boost-Type TCM PFC Rectifier – ETH Zurich

- Input Voltage: 184...264V<sub>AC</sub>
- Output Voltage: 400 V<sub>DC</sub>
  Rated Power: 3.3 kW
- Triple-Interleaved Topology
- 4.5kW/dm<sup>3</sup> (73.8W/in<sup>3</sup>) 15.0cm x 12.0cm x 4.0cm
- 98.8% Peak Efficiency









# ► Ultra-High Efficiency (2)

Cinfineon PFC Rectifier Evaluation Board

- Input Voltage: 85...265V<sub>AC</sub>
- Output Voltage: 400 V<sub>pc</sub>
   Rated Power: 2.5 kW
- CoolGaN<sup>TM</sup> CoolMOS<sup>TM</sup> C7

- → 70mΩ / 600V (GaN HEMTs) → 33mΩ / 650V (Silicon SJ technology)
- $\rightarrow$  @ 65kHz CCM (Hard-Switching)
- Totem-Pole Full-Bridge Topology
   Fulfills EMI CISPR Class B







# ► Ultra-High Efficiency (2)

Cinfineon PFC Rectifier Evaluation Board

- Input Voltage: 85...265V<sub>AC</sub>
- Output Voltage: 400 V<sub>DC</sub>
   Rated Power: 2.5 kW
- 3.76kW/dm<sup>3</sup> (61.7W/in<sup>3</sup>) 22.0cm x 7.2cm x 4.2cm
- f<sub>s</sub> = 65kHz (PWM → Soft + Hard Switching)
   99.1% Peak Efficiency









# ► Ultra-High Efficiency (3)

Interleaved TCM PFC Rectifier – ETH Zurich

- Output Voltage: 400 V<sub>DC</sub>
   Rated Power: 3.3 kW
- ZVS in All Bridges
- Large effective f<sub>s</sub> for Filter
   High Partial Load Efficiency (>99% for P>500W)
- Fulfills EMI CISPR Class B
- Only Si SJ MOSFETs → No SiC devices
- 1.20kW/dm<sup>3</sup> (19.7W/in<sup>3</sup>) f<sub>s</sub> max. 100kHz

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- 99.36% Peak Efficiency









# ► Ultra-High Power Density (1)

- > GLBC: ETH Zurich (1.0)
  - System Employing Active CeraLink<sup>™</sup> **1-Power Pulsation Buffer**
  - Interleaving of 2 Bridge Legs per Phase



- 8.2kW/dm<sup>3</sup> (135W/in<sup>3</sup>) 8.9cm x 8.8cm x 3.1cm
- $f_{\rm s} = 250 \, \text{kHz} \dots 1 \, \text{MHz}$
- 96,3% Peak Efficiency @ 2kW
- T\_=58 °C @ 2kW
- Compliant to All "Original" Specifications (!)
- i<sub>gnd</sub> < 5mA (!)</li>
   No Low-Frequ. CM Output Voltage Component
- No Overstressing of Components
- All Own IP / Patents



# ► Ultra-High Power Density (1)

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- *i*<sub>gnd</sub> < 5mA (!)</li>
  No Low-Frequ. CM Output Voltage Component
  No Overstressing of Components
- All Own IP / Patents





# ► Ultra-High Power Density (2)

- ➤ GLBC: ETH Zurich (2.0)
  - Alternative Converter Topology: DC/ | AC | Buck Converter + Unfolder
  - 60Hz Unfolder
  - TCM or PWM of DC/ |AC| Buck Converter
     X6S capacitors instead of Ceralink<sup>™</sup>

DC/ |AC| + Unfolder
 → Best Performance
 2 Switching Bridge Legs
 → Larger Volume & Losses
 → Not advantageous







# ► Ultra-High Power Density (2)

- ➤ GLBC: ETH Zurich (2.0)
  - Performance of First DC/ | AC | + Unfolder Prototype

  - PWM OperationWithout Power Pulsation Buffer
  - 14.8kW/dm<sup>3</sup> (243W/in<sup>3</sup>) 6.0cm x 5.0cm x 4.5cm

  - $f_{\rm s} = 250 \, \rm kHz$
  - 97.8% Peak Efficiency @ 2kW





![](_page_12_Picture_12.jpeg)

# ► Ultra-High Power Density (3)

- GLBC: Fraunhofer IISB
  - Very Well Engineered:
    - 3D Printed Heatsinks w/ Integrated Fans
    - 1 PCB Board
  - Multi-Airgap Inductors
  - 900 V SiC with PWM (Soft + Hard Switching)
    Buck-Type DC-side Power Pulsation Buffer

  - 12.2kW/dm<sup>3</sup> (201W/in<sup>3</sup>) *f*<sub>S</sub> = 140kHz 96.9% Peak Efficiency

![](_page_13_Figure_12.jpeg)

![](_page_13_Figure_13.jpeg)

![](_page_13_Figure_14.jpeg)

![](_page_13_Picture_15.jpeg)

# ► Ultra-High Power Density (4)

> GLBC: UIUC (Prof. Pilawa)

![](_page_14_Picture_3.jpeg)

- Multi-Level Topology: Flying Capacitor Converter (FCC) Seven-Level Output Voltage: Smaller Output Filter
- Low-Voltage (150V) GaN Switches (EPC 2033)
- 60Hz-Unfolder
- Full-Bridge Active Power Buffer

![](_page_14_Figure_9.jpeg)

# ► Ultra-High Power Density (4)

- ➢ GLBC: UIUC (Prof. Pilawa)
  - Careful Design of Switching Cells  $\rightarrow$ - Modularity
    - Reduced Parasitic Inductance
    - Reduced Switching Overvoltage

![](_page_15_Figure_6.jpeg)

- 13.2kW/dm<sup>3</sup> (216W/in<sup>3</sup>) 10.2cm x 6.1cm x 2.4cm
- f<sub>s</sub> = 120kHz (effective 720kHz)
   97.6% Peak Efficiency

![](_page_15_Picture_11.jpeg)

![](_page_15_Picture_12.jpeg)

## Performance Drivers for High Efficiency

#### 1. Power Pulsation Buffer (PPB)

- Analysis for Google Little Box Challenge (ΔV/V < 3%)</li>
   Efficiency Benefit of PPB→ For High Power Density (ρ > 9kW/dm<sup>3</sup>)

![](_page_16_Figure_5.jpeg)

Electrolytics Favorable for High Efficiency @ Moderate Power Density ( $\Delta \eta$ = +0.5%) • Electrolytics Show Lower Vol. & Lower Losses if Large  $\Delta V/V$  is accepted

# Performance Drivers for High Efficiency

#### 2. TCM vs. CCM

- TCM:
  - + Low (Soft) Switching Losses
  - Larger RMS Currents in Inductor and Switches

![](_page_17_Figure_6.jpeg)

- CCM (PWM):
  - + Lower RMS Currents in Inductor and Switches
  - High (Hard) Switching Losses

![](_page_17_Figure_10.jpeg)

**Not a clear winner**  $\rightarrow$  Case Dependent and Has To Be Optimized Optimization for GaN GIT & No Interleaving  $\rightarrow$  Optimal Inductors:  $L_{TCM} = 10\mu$ H and  $L_{CCM} = 30\mu$ H

![](_page_17_Figure_12.jpeg)

![](_page_17_Picture_13.jpeg)

#### ► Performance Drivers for High Efficiency

![](_page_18_Figure_2.jpeg)

# ► Performance Drivers for High Efficiency

3. Low Switching Frequency... But High Effective Switching Frequency

![](_page_19_Figure_3.jpeg)

# Performance Drivers for High Efficiency

3. Low Switching Frequency... But High Effective Switching Frequency

![](_page_20_Figure_3.jpeg)

Source: Pilawa

## ► Performance Drivers for High Efficiency

3. Low Switching Frequency... But High Effective Switching Frequency

![](_page_21_Figure_3.jpeg)

# Multi-Level Solutions Ultra-High Efficiency

- Specifications
- Motivation for Multi-Level
- Bridge Leg Comparison

![](_page_22_Picture_5.jpeg)

![](_page_22_Picture_6.jpeg)

## ► Specifications

Nom. Power	10 kW
Max. Power	12.5 kW
<b>V</b> <sub>DC,nominal</sub>	720 V (max. 800V)
<b>V</b> <sub>AC,nominal,RMS</sub>	230 V
Operation Mode	DC/AC (bidirectional)
EMI Filtering	Class A
# Phases	3

![](_page_23_Figure_3.jpeg)

- Can 99.5 % peak efficiency be reached?
- At what price (volume, weight and cost)?

![](_page_23_Figure_6.jpeg)

![](_page_23_Figure_7.jpeg)

![](_page_23_Figure_8.jpeg)

— 24/71 —

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# DC-Link Voltage: 400V...800V

- What is the Challenge from 400V<sub>DC</sub> to 800 V<sub>DC</sub>?
- $\rightarrow$  For the same AC-side power:
- Semiconductor Switching Losses
  - Switched Currents Don't Change
  - Switched Voltage Changes
- Semiconductor Conduction Losses
  - **RMS Current** in Half-Bridge Doesn't Change
  - Semicond. On-State Resistance Changes
- Capacitor Voltage Rating Series Connection
  - Volume Quadratic With # of Series Connected Capacitors for Same C
  - Passive (Resistive) Voltage Balancing

![](_page_24_Figure_13.jpeg)

![](_page_24_Picture_14.jpeg)

#### Motivation for Multi-Level Topologies

Analyze best strategy to achieve target 99.5% efficiency

![](_page_25_Figure_3.jpeg)

▲ 2-Level Bridge Leg

![](_page_25_Figure_5.jpeg)

![](_page_25_Picture_6.jpeg)

#### Motivation for Multi-Level Topologies

#### Analyze best strategy to achieve target 99.5% efficiency

![](_page_26_Figure_3.jpeg)

#### Motivation for Multi-Level Topologies

#### Analyze best strategy to achieve target 99.5% efficiency

![](_page_27_Figure_3.jpeg)

A 7-Level FC Bridge Leg

#### Three main advantages

- 1. More output voltage levels
- 2. Higher effective frequency

# Smaller magnetics

![](_page_27_Figure_9.jpeg)

3. Better switch utilization (LV switches outperform HV switches)

# Bridge Leg Analysis – 99.5% Efficiency Target

- Optimum Number of Levels?
- Compared topologies:
  - 2 Level
  - 2 Level-Interleaved (3 Level)
  - 3 Level T-type
  - 3, 5 and 7 Level Flying Cap. Converter (FCC)
  - 5 and 7 Level Hybrid Active NPC (HANPC)

![](_page_28_Figure_9.jpeg)

![](_page_28_Figure_10.jpeg)

#### Result of the Bridge Leg Analysis – 99.5% Efficiency Target

![](_page_29_Figure_2.jpeg)

• Aim: topologies with highest power density (lowest volume).

#### Conclusions:

- ✓ 3L T-type: Good trade-off between magnetics and semiconductors. No capacitors.
- ✓ 7L HANPC: Good trade-off between capacitors and semiconductors. Small magnetics.

#### ► Hardware prototypes

![](_page_30_Figure_2.jpeg)

1.06 kW/kg (11.8 kg)

- % (measured) 99.5 % (expected)

2.63 kW/kg (4.8 kg)

99.35 % (measured) 99.37 % (expected)

31/71 —

# 7-Level HANPC Inverter Topology

![](_page_31_Picture_2.jpeg)

■ The **HANPC** topology can be **derived from** the Flying Capacitor Converter (**FCC**)

![](_page_32_Figure_3.jpeg)

![](_page_32_Picture_4.jpeg)

■ The **HANPC** topology can be **derived from** the Flying Capacitor Converter (FCC)

![](_page_33_Figure_3.jpeg)

■ The HANPC topology can be derived from the Flying Capacitor Converter (FCC)

![](_page_34_Figure_3.jpeg)

35/71 —

■ The HANPC topology can be derived from the Flying Capacitor Converter (FCC)

![](_page_35_Figure_3.jpeg)

#### ► HANPC topology

#### ANPC stage clamps the FC stage to the high-side and low-side DC-link on 50 Hz basis

U > 0

![](_page_36_Figure_4.jpeg)

![](_page_36_Figure_5.jpeg)

![](_page_36_Figure_6.jpeg)

![](_page_36_Figure_7.jpeg)

![](_page_36_Figure_8.jpeg)

# 7-Level HANPC Pareto Optimization

![](_page_37_Picture_2.jpeg)

![](_page_37_Picture_4.jpeg)

#### Switching Loss Data

Accurate and Reliable Switching Data is Necessary

- Specially when Switches Account for 60..70% of Total Losses
- LV semiconductor datasheets provide no data
- > Switching losses <u>have</u> to be measured

![](_page_38_Picture_6.jpeg)

#### Switching Loss Measurement Method

- Half-Bridge "In-The-Box"
- Brass Block as Heat-Sink
- Measure Elapsed Time to Heat-Up Block △T

![](_page_39_Figure_5.jpeg)

🔺 Thermal Circuit

![](_page_39_Figure_7.jpeg)

![](_page_39_Picture_8.jpeg)

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#### Switching Loss Measurement Method

- Half-Bridge "In-The-Box"
- Brass Block as Heat-Sink
- Measure Elapsed Time to Heat-Up Block △T

![](_page_40_Figure_5.jpeg)

Simplified Thermal Circuit

R-C

**Characteristic** 

![](_page_40_Figure_7.jpeg)

![](_page_40_Figure_8.jpeg)

![](_page_40_Picture_9.jpeg)

![](_page_40_Picture_10.jpeg)

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#### Switching Loss Measurement Method

- Half-Bridge "In-The-Box"
- Brass Block as Heat-Sink
- Measure Elapsed Time to Heat-Up Block △T

![](_page_41_Figure_5.jpeg)

Simplified Thermal Circuit

![](_page_41_Figure_7.jpeg)

![](_page_41_Figure_8.jpeg)

![](_page_41_Figure_9.jpeg)

![](_page_41_Figure_10.jpeg)

#### **Switching Loss Measurement Results**

#### Obtained Data is Used in Optimization

![](_page_42_Picture_3.jpeg)

12 California

Silicon FD 200V 11.1mΩ (*Infineon*)

#### **Switching Loss Measurement Results**

#### Obtained Data is Used in Optimization

![](_page_43_Figure_3.jpeg)

![](_page_43_Picture_4.jpeg)

Silicon FD 200V 11.1mΩ (*Infineon*)

![](_page_43_Figure_6.jpeg)

![](_page_43_Figure_7.jpeg)

#### **Switching Loss Measurement Results**

#### Obtained Data is Used in Optimization

![](_page_44_Figure_3.jpeg)

![](_page_44_Picture_4.jpeg)

Silicon FD 200V 11.1mΩ (*Infineon*)

![](_page_44_Figure_6.jpeg)

GaN 200V 10mΩ (*EPC 2047*)

![](_page_44_Picture_8.jpeg)

SiC 900V 10mΩ (*Wolfspeed*)

# **Flying Capacitors**

#### Dimensioning Criteria:

$$C_{\rm FC,min} = \frac{I_{\rm ac,pk}}{N_{\rm FCcell} f_{\rm sw} \Delta U_{\rm FC,max}}$$

- Max. Voltage Ripple:
  - $\Delta U_{FC,max} = 5V$  (arbitrary)
- Switching Freq.:
  - Highly Affects Cap. Requirement
  - Key Volume Contribution

![](_page_45_Figure_9.jpeg)

$$t_{\rm FC,max} = \frac{1}{N_{\rm FCcell} f_{\rm sw}}$$

# ► Flying Capacitors: Capacitor Type Selection

#### Charge Density:

![](_page_46_Figure_3.jpeg)

 $Q = C \cdot V$ 

![](_page_46_Figure_5.jpeg)

![](_page_46_Figure_6.jpeg)

![](_page_46_Figure_7.jpeg)

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# ► Flying Capacitors: Capacitor Type Selection

# Key Factors:

#### Capacitance Density:

![](_page_47_Figure_4.jpeg)

#### Price/Capacitance Ratio:

![](_page_47_Figure_6.jpeg)

- Key Technical Factor for Choosing Capacitor, Not Charge or Energy Density
- Electrolytic Seem the Best... But
  - Losses
  - Current Rating
  - Reliability/Lifetime...
- Ceramic are a Good Alternative for High Switching Frequencies
  - Capacitance Derating (30% assumed)
  - Price
  - Stacking of Ceramic Capacitors
  - Losses (problem for LF AC)
- Film are a Good Alternative for Low Switching Frequencies
  - Bulky

# ► Optimization: Considerations

- Semiconductors
  - ANPC Stage (50/60 Hz): Silicon
  - FC Stage (f<sub>sw</sub>): 3 x Silicon + GaN

#### Magnetics

- Nanocrystalline Cores
- Helical Windings

#### EMI Filter

• L-C structure (Simultaneous DM+CM Attenuation)

#### Topology variation

• Low-Voltage Switch Configuration for ANPC Stage: Same Voltage Level Switches in all Converter

#### Final EMI Filter Stage

![](_page_48_Figure_13.jpeg)

![](_page_48_Figure_14.jpeg)

![](_page_48_Figure_15.jpeg)

![](_page_48_Figure_16.jpeg)

🔺 Ľótva Voltage Svitch Bgidge theg Abb Picépt ger ANPC Stage

#### ► Optimization: Results

![](_page_49_Figure_2.jpeg)

![](_page_49_Figure_3.jpeg)

![](_page_49_Figure_4.jpeg)

#### ► Optimization: Results

![](_page_50_Figure_2.jpeg)

A Pareto Front Optimization Results ( $\eta @$  10 kW)

FCC Stage: 2 × Next Gen. Silicon (Infineo	on) 🛕
<b>f</b> <sub>sw</sub> 16 kHz	

![](_page_51_Picture_0.jpeg)

# 99.35 % Ultra-Efficient 7-Level HANPC Measurements

![](_page_51_Picture_2.jpeg)

![](_page_51_Picture_3.jpeg)

![](_page_51_Picture_4.jpeg)

#### ► Commutation Path

![](_page_52_Figure_2.jpeg)

**7L-HANPC Hardware Prototype** 

![](_page_52_Picture_4.jpeg)

#### Semiconductor Layout on the Power PCB

# **3.34 kW/dm<sup>3</sup> (55.9 W/in<sup>3</sup>)**

![](_page_53_Figure_3.jpeg)

A 7L-HANPC Hardware Prototype

![](_page_53_Picture_5.jpeg)

![](_page_53_Picture_6.jpeg)

![](_page_53_Figure_7.jpeg)

#### A 7-Level Output Voltage and Phase Currents @ 10 kW

#### **Final Results – Efficiency Measurements**

![](_page_54_Figure_3.jpeg)

Measured Efficiency in Steady-State @ V<sub>DC</sub> = 720V and V<sub>DC</sub> = 650V

![](_page_54_Picture_5.jpeg)

![](_page_54_Picture_6.jpeg)

# **Electric** vs. **Calorimetric** Efficiency Measurements

Large Uncertainty in Loss Determination with Electric Efficiency Measurement

![](_page_55_Figure_3.jpeg)

In This Case, Both Efficiency Measurement Methods Match, But Uncertainty is Too Large

![](_page_55_Picture_5.jpeg)

🔺 Yokogawa WT3000 Precision Power Analyzer

![](_page_55_Picture_7.jpeg)

#### **Final Results – EMI Measurements**

#### Hardware Passes EMI CISPR Class A Requirements

![](_page_56_Figure_3.jpeg)

![](_page_56_Picture_4.jpeg)

#### Measured EMI Spectrum with the Quasi-Peak (QPK) and Average (AVG) Test Receivers.

![](_page_57_Figure_2.jpeg)

Wide Band-Gap (WBG) Technology

![](_page_58_Figure_3.jpeg)

#### Silicon Technology

![](_page_59_Figure_3.jpeg)

#### > System Comparison

![](_page_60_Figure_3.jpeg)

> System Comparison  $\rightarrow$  25% Volume Addition for DC-Link 100Hz Power Buffering

![](_page_61_Figure_3.jpeg)

#### > System Comparison $\rightarrow$ 25% Volume Addition for DC-Link 100Hz Power Buffering

![](_page_62_Figure_3.jpeg)

#### > System Comparison $\rightarrow$ 25% Volume Addition for DC-Link 100Hz Power Buffering

![](_page_63_Figure_3.jpeg)

# Conclusion: Road towards the Future

![](_page_64_Picture_2.jpeg)

![](_page_64_Picture_3.jpeg)

#### ► Conclusion

- Multi-Level Converters are Adequate for Ultra-High Efficiency Applications
- Efficiency Barriers Pushed
  - 99.35% Peak Efficiency
  - European Weighted Efficiency  $\approx$  **99.10%**
  - California Energy Commission (CEC) Weighted Efficiency  $\approx \textbf{99.20\%}$
- Ultra-High Efficiency is Achievable with Off-The-Shelf Silicon Semiconductors
- 99.5% Efficiency can be Reached with Next-Generation Silicon Devices
- **99.5+% Efficiency** can be Reached with Commercial **GaN** Devices

![](_page_65_Picture_10.jpeg)

![](_page_65_Picture_11.jpeg)

## ► Performance Limits & Future Requirements

- Losses:
- Semiconductors
  - 66% of the Losses
  - WBG: Better on Paper... But in Reality?
  - Advanced Packaging → "Ideal Switch"
- Control

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- Low Power μC and/or FPGA/CPLD
- Every Watt Counts...

![](_page_66_Figure_10.jpeg)

(Efficiency)

🔺 Transition Towards Ideal Gate Driver and Package

# ► Performance Limits & Future Requirements

- Losses:
- Semiconductors
  - 66% of the Losses
  - WBG: Better on Paper... But in Reality?
  - Advanced Packaging → "Ideal Switch"
- Control
  - Low Power μC and/or FPGA/CPLD
- Every Watt Counts...
- > Volume:
- Capacitors
  - Determine the Volume for Low Sw. Freq. Converters
  - -0.2% in Efficiency  $\rightarrow$  +50% Power Density
- High Efficiency → No Heat-Sink
- Building Blocks: Standardized and Low Cost

![](_page_67_Picture_16.jpeg)

![](_page_67_Figure_17.jpeg)

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![](_page_69_Picture_1.jpeg)

![](_page_69_Picture_2.jpeg)

**Jon Azurza Anderson** (SM'16) received his B.Sc. degree in Industrial Technology Engineering from TECNUN School of Engineering of the University of Navarra in 2014, and his M.Sc. degree in Electrical Engineering from ETH Zurich (with distinction) in 2016, specializing in energy and power electronics. In 2013 and 2014 he worked for Fraunhofer IIS in Nuremberg, Germany, developing software in the RFID & Radio Systems group. In November 2016 he joined the Power Electronics Systems Laboratory (PES) as a scientific assistant, where in February 2017 he began his Ph.D. studies, focusing on ultra-high efficiency three-phase multi-level PWM converters.

![](_page_69_Picture_4.jpeg)

**Mattia Guacci** (SM'16) studied Electronic Engineering at the University of Udine, Italy where in July 2013 and in October 2015 he received his B.Sc. summa cum laude and his M.Sc. Summa cum laude, respectively. In 2014 he was with Metasystems SpA in Reggio nell'Emilia, Italy working on on-board battery chargers for electric vehicles. In November 2015 he joined the Power Electronic Systems Laboratory (PES) at ETH Zurich as a scientific assistant investigating innovative inverter topologies. In September 2016 he started his Ph.D. at PES focusing on advanced power electronics concepts for future aircraft and electric vehicle applications.

![](_page_69_Picture_6.jpeg)

**Dominik Neumayr** (SM'10) started his academic education at the University of Applied Sciences (FH) for Automation Engineering in Wels and received the Dipl.-Ing. (FH) degree in 2008. He was with the Center for Advanced Power Systems (CAPS) in Tallahassee/Florida working on Power/Controller Hardware-in-the-Loop simulations and control systems design for AC/DC/AC PEBB based converter systems from ABB. He continued his academic education at the Swiss Federal Institute of Technology in Zurich (ETH Zurich) and received the M.Sc. degrees in electrical engineering and information technology in 2015. Since spring 2015 he is a PhD student at the Power Electronic Systems (PES) Laboratory, ETH Zurich. His current research focuses on ultra-high power density converter systems.

![](_page_69_Picture_8.jpeg)

**Johann W. Kolar** (F<sup>10</sup>) received his Ph.D. degree (summa cum laude) from the Vienna University of Technology, Austria. He is currently a Full Professor and the Head of the Power Electronic Systems Laboratory at the Swiss Federal Institute of Technology (ETH) Zurich. He has proposed numerous novel PWM converter topologies, and modulation and control concepts and has supervised 70+ Ph.D. students. He has published 880+ scientific papers in international journals and conference proceedings, 4 book chapters, and has filed 190+ patents. He has received 26 IEEE Transactions and Conference Prize Paper Awards, the 2014 IEEE Power Electronics Society R. David Middlebrook Achievement Award, the 2016 IEEE William E. Newell Power Electronics Award, and the 2016 IEEE PEMC Council Award. He has initiated and/or is the founder of 4 ETH Spin-off companies.

**ETH** zürich

![](_page_70_Picture_1.jpeg)

# **Thank You**

![](_page_70_Figure_3.jpeg)

![](_page_70_Picture_4.jpeg)

Feb. 20<sup>th</sup>, 2019

![](_page_70_Picture_6.jpeg)